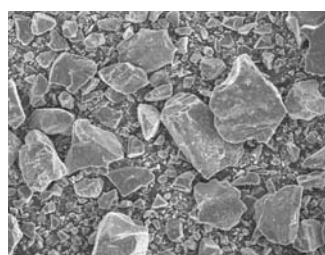
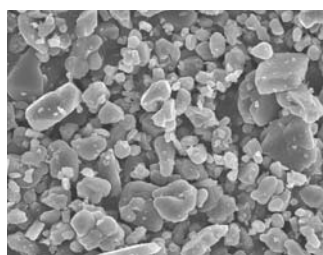
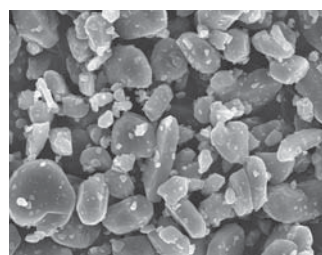
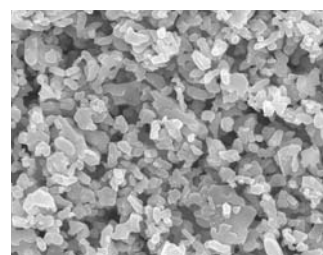


Filler Alumina

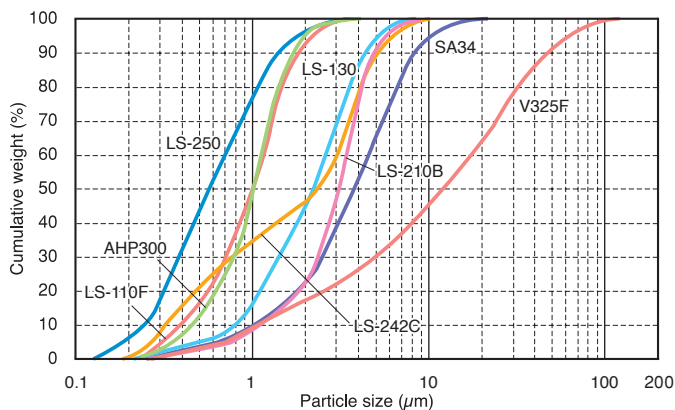
Alumina provides good electric insulation and thermal conductivity suitable for use in fillers for heat dissipation and molding compounds for packages. Various products are available with controlled particle shapes, particle size distribution and purity.

V325F
100μmLS-130
10μmLS-210B
10μmLS-250
5μm

Typical Properties

Grade	V325F	SA34	LS-110F	LS-130	LS-210B	LS-242C	LS-250	AHP300
LOI (%)	0.05	0.02	0.08	0.05	0.04	0.06	0.20	0.02
Na ₂ O (%)	0.13	0.37	0.05	0.03	0.07	0.07	0.06	Na15ppm
SiO ₂ (%)	0.12	0.03	0.09	0.07	0.03	0.03	0.03	Si 10ppm
Fe ₂ O ₃ (%)	0.03	0.02	0.03	0.03	0.02	0.03	0.02	Fe 4ppm
Al ₂ O ₃ (%)	99.7	99.6	99.9	99.9	99.9	99.9	99.9	99.99
Ave. Particle Size (μm)	12	4	1.1	2.2	3.1	2.3	0.6	1.0
α-Crystal Size (μm)	—	3~7	1~2	2~4	3~5	0.3~4.0	0.3	1.0~1.5
BET Specific Surface Area (m ² /g)	1.2	1.9	3.2	1.4	1.4	4.6	5.9	3.0
Oil Absorption (ml/100g)	16	25	26	28	21	22	30	27
pH	9	10	9	9	9	10	9	7

Particle Size Distribution



Applications

- (1) Thermal conductive materials
- (2) Molding compounds for packages
- (3) Compounds

Packing

- Flexible container bag
- Paper bag
- Pail